

Data sheet acquired from Harris Semiconductor SCHS072

# CMOS BCD-to-7-Segment Latch Decoder Drivers

High-Voltage Types (20-Volt Rating)



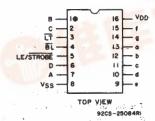


205-25087

CD4511B types are BCD-to-7-segment latch decoder drivers constructed with CMOS logic and n-p-n bipolar transistor output devices on a single monolithic structure. These devices combine the low quiescent power dissipation and high noise immunity features of RCA CMOS with n-p-n bipolar output transistors capable of sourcing up to the control of the co

Lamp Test (LT), Blanking (BL), and Latch Enable or Strobe inputs are provided to test the display, shut off or intensity-modulate it, and store or strobe a BCD code, respectively. Several different signals may be multiplexed and displayed when external multiplexing circuitry is used. The CD4511B is supplied in 16-lead hermetic dual-in-line ceramic packages (D and F suffixes), 16-lead dual-in-line plastic packages (E suffix), and in chip form (H suffix).

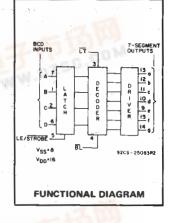
These devices are similar to the type MC14511.



CD45118 TERMINAL ASSIGNMENT

## Features:

- High-output-sourcing capability . . . . . . up to 25 mA
- Input latches for BCD Code storage
- Lamp Test and Blanking capability
- 7-segment outputs blanked for BCD input codes > 1001
- 100% tested for quiescent current at 20 V
- Max. input current of 1 μA at 18 V, over full package-temperature range, 100 nA at 18 V and 25°C
- 5-V, 10-V, and 15-V parametric ratings



## Applications:

- Driving common-cathode LED displays
- Multiplexing with common-cathode LED displays
- Driving incandescent displays
- Driving low-voltage fluorescent displays

MAXIMUM KATINGS, Absolute-Maximum Values:	
DC SUPPLY-VOLTAGE RANGE, (VDD)	
Voltages referenced to VSS Terminal)	0.5V to +20V
INPUT VOLTAGE RANGE, ALL INPUTS	
DC INPUT CURRENT, ANY ONE INPUT	±10mA
POWER DISSIPATION PER PACKAGE (PD):	
For T <sub>A</sub> = ~55°C to +100°C	
For T <sub>A</sub> = +100°C to +125°C	Derate Linearity at 12mW/°C to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR	
FOR TA = FULL PACKAGE-TEMPERATURE RANGE (All Packa	age Types) 100mW
OPERATING-TEMPERATURE RANGE (TA)	55°C to +125°C
STORAGE TEMPERATURE RANGE (Tstg)	65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):	
At distance 1/16 $\pm$ 1/32 inch (1.59 $\pm$ 0.79mm) from case for 10s	s max +265°C

## OPERATING CONDITIONS AT TA = 25°C Unless Otherwise Specified

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges

Characteristic	V <sub>DD</sub>	Min.	Max.	Units
Supply:Voltage Range (TA): (Full Package Temperature Range)	-	3	18	· V
.750.	5	150		ns
Set-Up Time (ts)	10	70	_	ns
	15	40		ns
	5	0	_	ns
Hold Time (t <sub>H</sub> )	10	0	_	ns
	15	0	-	ns
	5	400	_	ns
Strobe Pulse Width (t <sub>W</sub> )	10	160		ns
	15	100	_	ns



#### STATIC ELECTRICAL CHARACTERISTICS

	TE	ST CON	OITIO	NS										
					LIMITS AT INDICATED TEMPERATURES (°C)							1		
CHARACTERISTIC	Іон	v <sub>o</sub>	VIN	V <sub>DD</sub>				+25			Units			
	(mA)		(V)	(V)	<b>–55</b>	-40	+85	+125	Min.	Тур.	Max.			
Quiescent Device	_	_	_	5	5	5	150	150		0.04	5			
Current: IDD			_	10	10	10	300	300		0.04	10	μΑ		
Max.			_	15	20	20	600	600	_	0.04	20			
		_	_	20	100	100	3000	3000	_	0.08	100			
Output Voltage:		•												
			0,5	5			0.05		· -	0	0.05	-		
Low-Level VOL	_=_		0,10	10	0.05					-0	0.05	·V		
Max.	-	<u></u>	0,15	15	0.05				0	0.05	'			
	<u> </u>	-	0,5	5	4	4	4.2	4.2	4.1	4.55	L -			
High-Level V <sub>OH</sub>			0,10	10	9	9	9.2	9.2	9.1	9.55	_	V		
Min.			0.15	15	14	14	14.2.	14.2	14.1	14.55	-	<u></u>		
Input Low	_	0.5,3.8		5	1.5				_	_	1,5			
Voltage, VIL	_	1,8.8	-	10			3		_	-	3	1 v		
Max.	·	1.5,13.8		15			4		-	_	4	1		
Input High	-	0.5,3.8		5			3.5		3.5	_	<u> </u>	<u> </u>		
Voltage, V <sub>IH</sub>	_	1,8.8		10		7			7	_		v l		
Min.	-	1.5,13.8		15	11			11		-				
· · · · · · · · · · · · · · · · · · ·	0			A	4.0					4.55		l		
	5	-			4.0	4.0	7.20	4.20	4.10	4.25	<u> </u>			
	10	-		5	3.80	3.80	3.90	3.90	3.90	4.10		١.,		
	15		-	ī		-	3.50	3.50	-	3.95		V		
	20			1	3.55	3.55	3.30	-	3.40	3.75	_			
	25			↓	3.40	3.40	-	-	3.10	3.55	-			
	0			1	9.0	9.0	9.20	9.20	9.10	9.55				
Output Drive	5					-	-		-	9.25				
Voltage:	10	_	_	.	8.85	8.85	9.00	9.00	9.00	9.15	-	l v		
High Level VOH	15	-	-	10	_	_		'	_	9.05	_	<sup>v</sup>		
Min.	20	-	-		8.70	8.70	8.40	8.40	8.60	8.90				
	25	-	-		8.60	8.60	-	_	8.30	8.75	. –			
	0	_		4	14.0	14.0	14.20	14.20	14.10	14.55	_			
	5					-		-		14.30	_			
	10			15	13.90	13.90	14.0	14.0	14.0	14.20	-	l v		
	15			i			_	_		14.10		'		
	20				13.75	13.75	13.50	13.50	13.70	13.95	-			
	25		-		13.65	13.65	-		13.50	13.80	_			
Output Low				,				]						
(Sink) Current,		0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1		mA		
lor"		0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	_			
Min.		1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8				
Input Current, I <sub>IN</sub>	-	0,18	0,18	18	±0.1	±0.1	±1	±1	-	±10-5	±0.1	μΑ		
Max.	Щ.			L	L		L	Ь		L	نيسا	L		

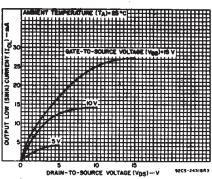


Fig. 1 — Typical output low (sink) current characteristics.

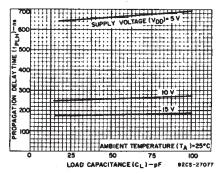


Fig. 2 — Typical data-to-output, low-to-high-level propagation delay time as a function of load capacitance.

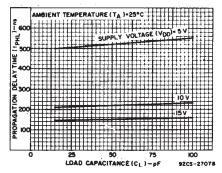


Fig. 3 — Typical data-to-output, high-to-low-level propagation delay time as a function of load capacitance.

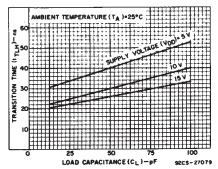


Fig. 4 — Typical low-to-high-level transition time as a function of load capacitance.

# DYNAMIC ELECTRICAL CHARACTERISTICS at T $_A$ = 25°C, Input t $_r$ , t $_f$ = 20 ns, C $_L$ = 50 pF, R $_L$ = 200 k $\Omega$

CHARACTERISTIC	Test Conditions	A	UNITS		
S (	Y <sub>DD</sub> Volts	Min.	Тур.	Max.	
Propagation Delay Time:	5	-	520	1040	
(Data)	10	-	210	420	ns
High-to-Low Level, tpHL	15	_	150	300	
	5	_	660	1320	
Low-to-High Level, tpLH	10	j –	260	520	ns
	15		180	360	L.,
Propagation Delay Time:	5	_	350	700	
(BL)	10	-	175	350	ns
High-to-Low Level, tpHL	15		125	250	
	5		400	800	
Low-to-High Level, tpLH	10	-	175	350	ns
	15		150	300	
Propagation Delay Time:	5	-	250	500	
(LT)	10	-	125	250	ns
High-to-Low Level, tpHL	15		85	170	<u> </u>
	5	-	150	300	
Low-to-High Level, tpLH	10	_	75	150	ns
	15	_	50	100	
Transition Time:	5	_	40	80	
	10	-	30	60	пѕ
Low-to-High Level, tTLH	15	_	25	50	
	5	-	125	310	
	10	_	75	185	ns
High-to-Low Level, tTHL	15	_	65	160	
• • • • • • • • • • • • • • • • • • •	5	150	75	-	
Minimum Set-Up Time, t <sub>S</sub>	10	70	35	-	ns
	15	40	20	_	
	5	0	-75	-	
Minimum Hold Time, tH	10	0	-35	_	ns
	15	0	-20	_	
a	5	400	200	-	
Strobe Pulse Width, t <sub>W</sub>	10	160	80	. —	ns
	15	100	50		
Input Capacitance, C <sub>IN</sub>		_	5	7.5	pF

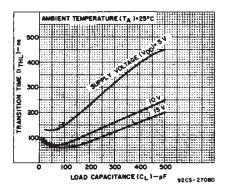


Fig. 5 — Typical high-to-low transition time as a function of load capacitance.

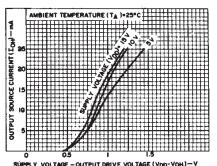


Fig. 6 — Typical voltage drop (V<sub>DD</sub> to output) vs.
output source current as a function of supply.

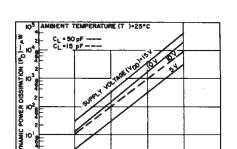
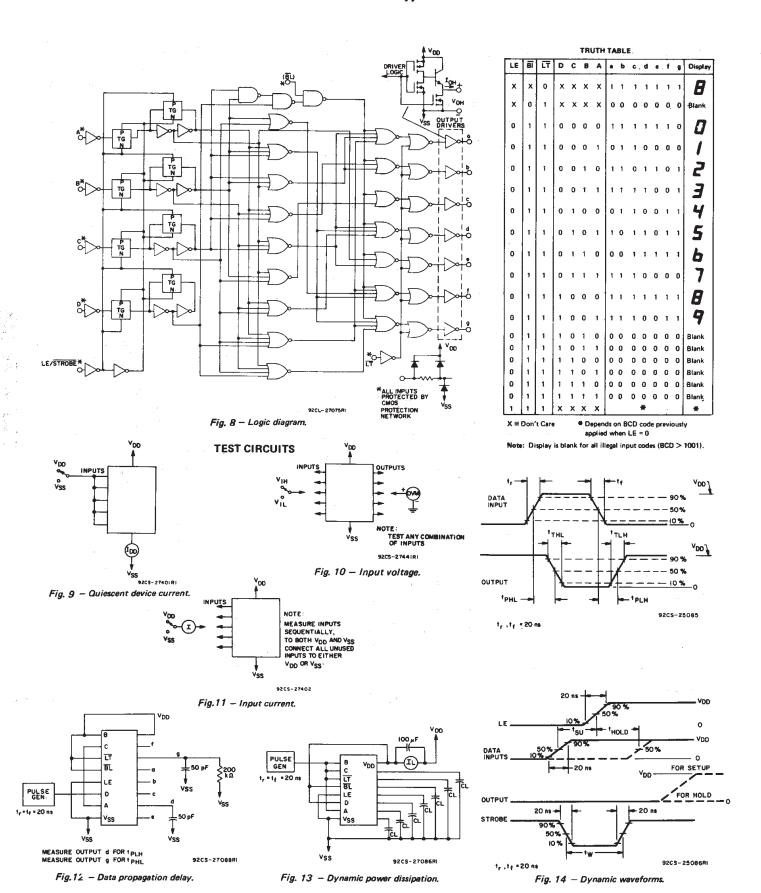
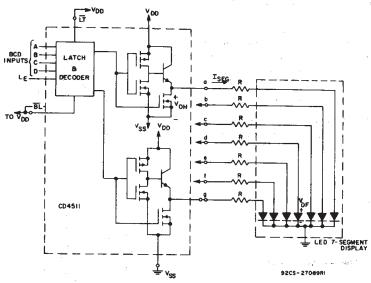


Fig. 7 — Typical dynamic power dissipation characteristics.

2 4 4 8 100 FREQUENCY (f) - kHz



## **APPLICATIONS** Interfacing with Various Displays

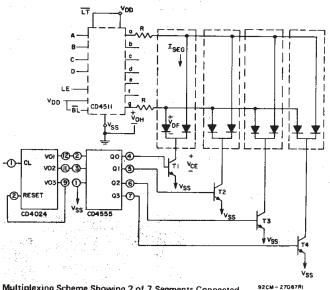


Duty Cycle = 100%

ISEG = IDIODEAVG. = 20 mA at Luminous Intensity/Segment = 250 microcandles

$$R = \frac{V_{OH} - V_{DF}}{I_{SEG}}$$

Fig. 15 - Driving common-cathode 7-segment LED displays (example Hewlet-Packard 5082-7740).



Multiplexing Scheme Showing 2 of 7 Segments Connected

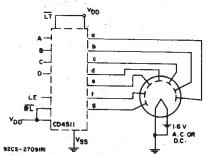
Transistors T<sub>1</sub>-T<sub>4</sub> (RCA-2N3053 or 2N2102) have I<sub>C</sub> Max.rating >7xI<sub>SEG</sub>

4 character display or 4 discrete Monosanto Man 3 displays).

Duty Cycle = 25%
$$|SEG = |IDIODE_{AVG}| \times 4$$

$$R = \frac{|V_{OH} - V_{DF} - V_{CE}|}{|SEG|}$$
All unused inputs on CD4555

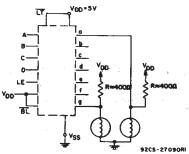
are connected to V<sub>DD</sub> or V<sub>SS</sub>. Fig. 18 — Multiplexing with common-cathode 7-segment LED displays (example Hewlet-Packard 5082-7404



A medium-brightness intensity display can be obtained with low-voltage fluorescent displays such as the Tung-Sol Digivac S/G\*\* Series.

\*\*Trademark Tung-Sol Division Wagner Electric Co.

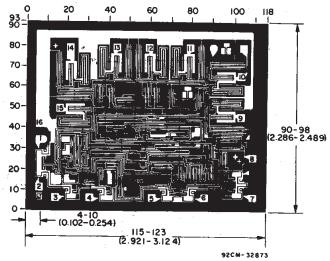
Fig. 16 - Driving low-voltage fluorescent displays.



2 of 7 Segments Shown Connected

Resistors R from V<sub>DD</sub> to each 7-segment driver output are chosen to keep all Numitron segments slightly on and warm.

Fig. 17 — Driving incandescent displays (RCA Numitron DR2000 series displays).



Dimensions and pad layout for CD45118 chip.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils ( $10^{-3}$  inch).

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